

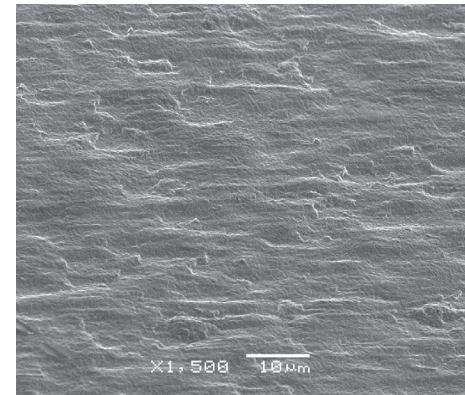
Low profile electrodeposited copper foil.

Applications:

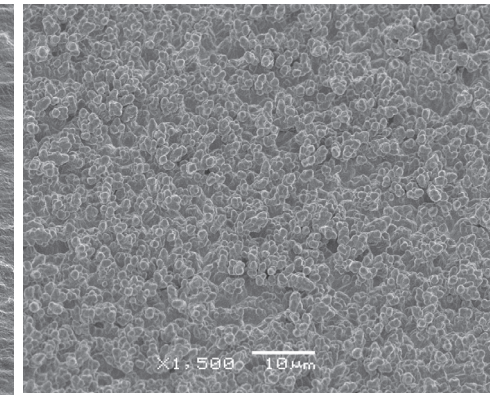
- PCB inner layers

Features:

- IPC Grade III
- Treatment on matte side of foil
- Excellent adhesion to a wide range of resin systems
- Arsenic free



Untreated Drum Side
H oz. /18 μm (1500x)



Treated Matte Side
H oz. /18 μm (1500x)

Typical Values:

| Attribute | | Unit | Value | | | Reference |
|--|------------------|-----------------------------|-------|--------|--------|---|
| Thickness Designation | | | H | 1 | 2 | IPC-4562, 1.2.5.1 Table 1-1; IPC-TM-650-2.2.12 |
| Nominal Thickness | | μm | 18 | 35 | 70 | |
| | | oz. | 1/2 | 1 | 2 | |
| Area Weight | | g/m^2 | 152.5 | 305 | 610 | |
| | | $\text{g}/254 \text{ in}^2$ | 25 | 50 | 100 | |
| | | oz./ft ² | 0.5 | 1 | 2 | |
| Roughness | Drum Side Ra | μm | 0.25 | | | IPC-TM-650-2.2.17 |
| | | $\mu\text{''}$ | 10 | | | |
| | Matte Side Rz | μm | 5.1 | 6.3 | 10.2 | |
| | | $\mu\text{''}$ | 200 | 250 | 400 | |
| Tensile | Ambient | Kg/mm^2 | 42.2 | 38.7 | 36.9 | IPC-TM-650-2.4.18 |
| | | Kpsi | 60 | 55 | 52.5 | |
| | 180°C | Kg/mm^2 | 21 | | | |
| | | Kpsi | 30 | | | |
| Elongation | Ambient | % | 8 | 15 | 20 | |
| | 180°C | % | 8 | | | |
| Peel Strength* (Matte/Treated Side) | Cond. B | Kg/cm | >0.71 | > 0.80 | > 0.89 | IPC-TM-650-2.4.8 |
| | | Lbs/in | > 4.0 | > 4.5 | > 5.0 | |

* Peel strength measured on 170°C Tg Epoxy

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